L Number	Hits	Search Text	DB	Time stamp
1	242	(leadframe frame (lead adj frame)) with (tiebar dambar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 03:03
3	116549	pad same "3"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 02:58
4	380647	"4" same (semiconductor chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 03:04
5	0	pad same (ring same ((leadframe frame (lead adj frame)) with (tiebar dambar)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 02:59
2	20	ring same ((leadframe frame (lead adj frame)) with (tiebar dambar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 02:59
6	41959	(leadframe frame (lead adj frame)) with ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 03:04
7	836	((leadframe frame (lead adj frame)) with ring) same pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 03:04
8	199	(((leadframe frame (lead adj frame)) with ring) same pad) same (semiconductor chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 03:04